



# Module 1

Quiz: Running code on the LaunchPad using CCS



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## Q1 Definitions

In 16 words or less give definitions of the following terms

- a) Memory read
- b) Memory write
- c) ROM
- d) Volatile
- e) RAM
- f) Port

## Q2 Real time

In 16 words or less give definitions of the following terms

- a) Hard real time
- b) Firm real time
- c) Soft real time

## Q3 Embedded system constraints

List five constraints that typically occur in embedded systems

## Q4 Code Composer Studio

In 16 words or less give definitions of the following operations

- a) Build: Compile and link
- b) Debug: Download and debug
- c) Single step
- d) Step over
- e) Step out

## Q5 RAM

Is RAM volatile or nonvolatile?

## Q6 Flash ROM

1.2 Is flash ROM volatile or nonvolatile?

## Q7 Definitions

For each term give a definition in 16 words or less: microprocessor, microcomputer, and microcontroller.

- a) Microprocessor
- b) Microcomputer
- c) Microcontroller

## Q8 Definitions

For each term give a definition in 16 words or less:

- a) Volatile
- b) Nonvolatile

## Q9 Processor

List the four components of a processor and define each in 16 words or less

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